

1. Record Nr.	UNISA996574960003316
Titolo	1838-2019 - IEEE Standard for Test Access Architecture for Three-Dimensional Stacked Integrated Circuits // Institute of Electrical and Electronics Engineers
Pubbl/distr/stampa	New York, New York : , : IEEE, , 2020
ISBN	1-5044-6343-9
Descrizione fisica	1 online resource (73 pages)
Disciplina	621.38132
Soggetti	Microwave transmission lines - Standards
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Sommario/riassunto	IEEE Std 1838 is a die-centric standard; it applies to a die that is intended to be part of a multi-die stack. This standard defines die-level features that, when compliant dies are brought together in a stack, comprise a stack-level architecture that enables transportation of control and data signals for the test of (1) intra-die circuitry and (2) inter-die interconnects in both (a) pre-stacking and (b) post-stacking situations, the latter for both partial and complete stacks in both pre-packaging, post-packaging, and board-level situations. The primary focus of inter-die interconnect technology addressed by this standard is through-silicon vias (TSVs); however, this does not preclude its use with other interconnect technologies such as wire-bonding.

2. Record Nr.	UNIORUON00409024
Autore	PETRESCU, Paul
Titolo	Arta populara romaneasca / Paul Petrescu, Georgeta Stoica
Pubbl/distr/stampa	Bucuresti, : Editura Meridiane, 1981
Descrizione fisica	146 p. : ill., tav. ; 21 cm.
Altri autori (Persone)	STOICA, Georgeta
Disciplina	700
Soggetti	ARTE ROMENA POPOLARE
Lingua di pubblicazione	Rumeno
Formato	Materiale a stampa
Livello bibliografico	Monografia